

RL78 Family CS+ Debugging Using Hot Plug-in Function

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Introduction

This document describes the procedures of debugging using the hot plug-in function provided in some RL78 family microcontrollers such as RL78/Fxx (RL78/F12 MCU does not support hot plug-in function.).

Tool settings and connection procedures when using CS+ for CA,CX, Renesas Flash Programmer, E1 emulator, hot-plug adapter (R0E000010ACB00), and CPU board (QB-R5F10BMG-TB) are described in detail in the order of program creation -> building -> debugging steps.

When using CS+ for CC, the hot plug-in method is same, so please refer to this document. But note that only <u>the hot plug-in initialization function</u> is different.

Remarks 1: For operations of CS+, refer to the CS+ User's Manual.

- 2: For information regarding the circuit for connecting the E1 to the user system and regarding the user resources to be used, refer to " Emulator User's Manual" (document number: R20UT1994).
- 3: For operations of the Renesas Flash Programmer, refer to the Renesas Flash Programmer User's Manual.



Figure 1 Overview of System



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1. Overview of Debugging Using Hot Plug-in Function

1.1 Features of Hot Plug-in Function

The hot plug-in function allows the debugger to be connected during user system operation with "program execution continued", "no reset applied", and "program contents not modified".

When a failure is found during inspection or after shipment of a user system, it can be debugged with the failure status retained through the hot plug-in function.

The following shows the main features of the hot plug-in function.

► Feature 1: The failure status can be retained.

When the debugger is connected,

- program execution can continue,
- no reset is generated, and
- program contents do not need to be modified.

► Feature 2: The program is protected by the security function.

- ID code authentication is done when the debugger is connected.
- ► Feature 3: Failures can be analyzed while operation continues.
 - After the debugger is connected, RAM monitoring using the DTC is possible without stopping the CPU operation.
- ► Feature 4: Detailed analysis is possible.
 - Forced break can be used.
 - After a break, software break or event break can be specified.
- Note: The hot plug-in function is aimed at failure analysis. Use the conventional on-chip debugging function in early stages of user program development.

1.2 Debugging after Hot Plug-in Connection

After hot plug-in connection of the debugger to the microcontroller that is operating, debugging can be done with the CPU operation continued through the RRM or DMM using the DTC dedicated to debugging.

The conventional RL78 microcontrollers use the CPU to access memory for debugging, but integrating the debug DTC on the chip enables memory access for debugging without using the CPU.

The following areas can be accessed through RRM/DMM using the DTC.

[Readable/writable resources]

- RAM
- SFRs

[Read-only resources]

- Data flash (only when reading is enabled)
- Mirror area
- General registers



Figure 2 Concept of Debug DTC

[Description of terms]

- DTC: Data transfer controller. This transfers data between memory units without CPU intervention.
- RRM: Realtime RAM monitor. This reads data from RAM or SFRs without stopping CPU operation.
- DMM: Dynamic memory modification. This writes to RAM or SFRs without stopping CPU operation.

2. Debugging Procedures Using Hot Plug-in Function

This section describes the procedures for debugging using the hot plug-in function.

2.1 Overview of Operation Procedures

The following shows the operation procedures. Install the CS+ before starting the procedures.



- 2.2 Actual Operations Using Hot Plug-in Function
- 2.2.1 Creating a Program that Allows Hot Plug-in Connection
- (1) Starting CS+

 $\label{eq:Select} \text{Select} \ [\text{Start}] \rightarrow [\text{Programs}] \rightarrow [\text{Renesas} \ \text{Electronics} \ \text{CS+}] \rightarrow [\text{CS+} \ \text{for} \ \text{CA,CX}] \ \text{to} \ \text{start} \ \text{CS+}.$

(2) Creating a Project

1.

• Create a new project from the start panel.

G	New Project A new project can be created. A new project can also be created by reusing the file configuration registered to an existing project. 1.
Start creation	Click the [GO] button under "Create New Project".

• Make detailed settings for the project.

Microcontroller: Using microcontroller:	RL78	Internal RO	e me:RSF10PMF M size(KBytes):96 M size(Bytes):8192		
		Product Na Internal RO	me:R5F10PMF M size[KBvtes]:96		•
RL78/F13 (ROM:96KB) RL78/F13 (ROM:96KB) RL78/F14 (ROM:48KB) RL78/F14 (ROM:48KB) RL78/F14 (ROM:46KB) RL78/F14 (ROM:96KB) RL78/F14 (ROM:96KB) RC78/F10PGF(48pin) RF10PGF(48pin)		Product Na Internal RO	me:R5F10PMF M size[KBvtes]:96		*
RL78/F13 (ROM:128KB) R178/F14 (ROM:48KB) R78/F14 (ROM:48KB) R178/F14 (ROM:64KB) R75/F14 (ROM:96KB) R5F10PGF(48pin) R5F10PGF(48pin)		Internal RO	M size[KBytes]:96		*
R5F10PMF(80pin)		1 .			
					Ŧ
Kind of project	Application(CA	78KOR)			
Project name:	sample		2.		
Place:	C:\			•	Browse
5	Z Make the pro	piect folder.)	3.		
C:\sample\sample.mtpj					
Page the file composition of a	n existing proje	ct to the new p	roject		
Project to be passed:	(Input project fi	le to be diverte	id.)	.	Browse
Cgpy composition files in the	diverted proje	ct folder to a ne	4 .		
		Create	Cancel		Help

1.	Specify [Using microcontroller]	Select the name of the device to be used. In this example, "R5F10PMF(80pin)" is selected.
2.	Specify [Project name]	A desired name can be specified. In this example, "sample" is specified.
3.	Specify [Place]	A desired place can be specified. In this example, "C:¥" is specified.
4.	Create a project	Click the [Create] button.



(3) Creating a User Program

• Create the main.c file.

Project Tree	🕂 🗙 📝 Property			Add File
2 🕜 🤮 🗷	J File Property	1		File type:
Sample (Project) R5F10PMF (Microcontroller CA78K0R (Build Tool) L178 Simulator (Debug Too	Category na	Category Information Category name 2.		C source file (*.c) Header file (*.h; *.nc) Assemble file (*.arm) Link directive file (*.dr, *.dir) Variable and function information file (*.vfi) Text file (*.bt)
Add	• 🚺	Add File		
Open Folder with E	xplorer 🏼 🄊	Add New File		
🗉 Windows Explorer	Menu 🕙	Add New Category		
Remove from Proje	ct Shift+Delete			Empty C source file.
Сору	Ctrl+C			File name: main.c
🖺 Paste	Ctrl+V			File location: C.¥sample¥ 4. Refer
ajje Rename	F2			
Property				5. OK Cancel Help

1. Open the context menu for "File"	Select "File" in the project tree and then right-click it.
2. Add a new file	Select [Add] \rightarrow [Add New File].
3. Specify [File name]	A desired name can be specified. In this example, "main.c" is specified.
4. Specify [File location]	A desired location can be specified. In this example, "C:¥sample¥" is specified.
5. Create a file	Click the [OK] button.

• Edit the main.c file.





- (4) Creating the Hot Plug-in Initialization Function
 - Create a file for defining the hot plug-in initialization function (hpi_initialize_prog). Add the hpi_init.asm file to the project.



1. Open the context menu for "File"	Select "File" in the project tree and then right-click it.
2. Add a new file	Select [Add] \rightarrow [Add New File].
3. Specify [File name]	A desired name can be specified. In this example, "hpi_init.asm" is specified.
4. Specify [File location]	A desired location can be specified. In this example, "C:¥sample¥" is specified.
5. Create a file	Click the [OK] button.

• Edit the hot plug-in initialization function (hpi_initialize_prog).



1. Open "hpi_init.asm"	Double-click "hpi_init.asm" in the project tree.
2. Edit the hot plug-in initialization	Copy and paste the contents on the next page to the
function	hpi_init.asm file.

Note: The following shows the hot plug-in initialization function, which initializes and enables the DTC dedicated to debugging. Copy this function to the user program without change.

[How to Use Initialization Function]

- Call the function with the earliest possible timing after RAM initialization is completed. Execution of the initialization function should be completed within 400 ms after the CPU reset is canceled. If execution is not completed within this period, the debugger will hang when a pin reset or a POC reset occurs after hot plug-in connection.
- Call this function only once after a reset.
- As SFRs are manipulated in the initialization function, disable the SFR guard function before calling this function.
- In this initialization function, interrupts are disabled until the execution of the function is completed.
 When interrupts need to be enabled, delete three lines including "for disable interrupt" as comments.
 (When interrupts are enabled, take care of the time until the execution of the initialization function is completed and the stack size to be used.)

CS+ for CA,CX (RL78/F1x)

PUBLIC _hpi_initialize_prog				
_hpi_initiali	ize_prog: PUSH DI	PSW	;for disable interrupt ;for disable interrupt	
	PUSH PUSH PUSH MOV PUSH	AX DE HL A,ES AX		
MOV MOVW MOVW BT		ES,#000H DE,#000C HL, #0072 [HL].7,\$SE		
SET_TRCS	MOVW BR	HL,#00D0 \$SEC_CO		
SEC_CHK:	MOVW	HL,#00E0	Н	
	MOV BT	A,!0723H A.0, \$DTC	_DES_SET	
SEC_COD	MOV MOV INCW INCW MOVW CMPW SKZ BR	A,ES:[DE] [HL],A DE HL AX,DE AX,#000C \$SEC_CO		
DTC_DES_	_SET: MOV MOV MOVW MOVW MOV	ES,#00FH L,#00EH AX,#0FFA [HL],AX L,#010H		
DTC_SET:	MOV MOV MOV MOV MOV MOV MOV MOV MOV MOV	[HL+00H],; [HL+01H],; [HL+02H],; [HL+03H],; [HL+04H],; A,H [HL+05H],; [HL+06H],; [HL+07H],; [HL+08H],; [HL+0AH],	#001H #00AH #00AH #000H A #023H #007H #000H #000H	



RL78 Family CS+ Debugging Using Hot Plug-in Function

MOV MOV MOV MOV MOV MOV MOV MOV MOV MOV	[HL+0BH],#001H [HL+0CH],#023H [HL+0DH],#007H [HL+0EH],#0ADH [HL+0FH],#0FFH [HL+10H],#011H [HL+11H],#001H [HL+13H],#010H [HL+13H],#010H [HL+15H],#0FFH [HL+16H],#000H A,H [HL+17H],A [HL+17H],A [HL+18H],#003H [HL+19H],#010H [HL+110H],#010H [HL+110H],#010H [HL+110H],#010H [HL+110H],#010H [HL+110H],#010H [HL+110H],#010H [HL+110H],#010H [HL+110H],#05FH [HL+11F],#0FFH DTCEN
POP MOV POP POP POP POP	AX ES,A HL DE AX PSW ;for disable interrupt
RET END	

CS+ for CC (RL78/F1x)

. PUBLIC _hpi_initialize_prog
_hpi_initialize_prog: PUSH PSW ;for disable interrupt DI ;for disable interrupt PUSH AX PUSH DE PUSH HL MOV A,ES
PUSH AX MOV ES,#0x000 MOVW DE,#0x000C4 MOVW HL, #0x00722 BT [HL].7,\$SET_TRCSIZE1 SET_TRCSIZE0: MOVW HL,#0x00D00
BR \$SEC_CODE_SET SET_TRCSIZE1:
MOVW HL,#0x00E00 SEC_CHK: MOV A.!0x0723
BT A.0, \$DTC_DES_SET SEC_CODE_SET: MOV A,ES:[DE]
MOV [HL],A INCW DE INCW HL
MOWN AX,DE CMPW AX,#0x000CE SKZ
BR \$SEC_CODE_SET DTC_DES_SET: MOV ES.#0x00F
MOV L,#0x00E MOVW AX,#0x0FFAD
MOVW [HL],AX MOV L,#0x010 DTC SET:
MOV [HL+0x02],#0x00A MOV [HL+0x03],#0x00A MOV [HL+0x04],#0x000
MOV A,H MOV [HL+0x05],A MOV [HL+0x06],#0x023
MOV [HL+0x07],#0x007 MOV [HL+0x08],#0x000



MOV [HL+0x09],#0x00	
MOV [HL+0x0A],#0x00	
MOV [HL+0x0B],#0x00	01
MOV [HL+0x0C],#0x02	
MOV [HL+0x0D],#0x00	
MOV [HL+0x0E],#0x0/	
MOV [HL+0x0F],#0x0F	
MOV [HL+0x10],#0x01	
MOV [HL+0x11],#0x00	
MOV [HL+0x12],#0x01	
MOV [HL+0x13],#0x01	0
MOV [HL+0x14],#0x0A	
MOV [HL+0x15],#0x0F	
MOV [HL+0x16],#0x00	00
MOV A,H	
MOV [HL+0x17],A	
MOV [HL+0x18],#0x00	
MOV [HL+0x19],#0x00	
MOV [HL+0x1A],#0x07	
MOV [HL+0x1B],#0x01	
MOV [HL+0x1C],#0x00	00
MOV A,H	
MOV [HL+0x1D],A	
MOV [HL+0x1E],#0x0/	
MOV [HL+0x1F],#0x0F	F
SET1 IDTCEN	
POP AX	
MOV ES,A	
POP HL	
POP DE	
POP AX	
POP PSW	;for disable interrupt
RET	

CS+ for CC (RL78/F2x)

.PU	JBLIC _hpi_initialize_prog_f2>	< c
_hp	pi_initialize_prog_f2x: PUSH PSW DI PUSH AX PUSH DE PUSH HL MOV A,ES PUSH AX MOV ES,#0x000 MOVW DE,#0x000C	;for disable interrupt ;for disable interrupt
	MOV A,ES:[DE] BT A.2,\$GO_SETHP	1
GO	BR \$!NOHPISET_RE SETHPI: MOVW DE,#0x000C	
	MOVW DE,#0x00000 MOVW HL, #0x0072 BT [HL].7,\$SET TRO	2
SET	T_TRCSIZE0: MOVW HL,#0x00D00	
SET	BR \$SEC_CHK T_TRCSIZE1: MOVW HL,#0x00E00)
SEC	C_CHK: MOV A,!0x0723	
SEC	BT A.0, \$DTC_DES_ C_CODE_SET: MOV A,ES:[DE] MOV (HL],A	SET
	INCW DE INCW HL	
	MOVW AX,DE CMPW AX,#0x000D6 SKZ	6
	BR \$SEC_CODE_SE BR \$DTC_SET_SUB	
DTO	C_DES_SET: MOV ES,#0x00F MOV L,#0x00E	
	MOV L,#0x00E MOVW AX,#0x0FFA MOVW [HL],AX	D
	C_SET_SUB: MOV L,#0x010	
DTO	C_SET: MOV [HL+0x00],#0x0 MOV [HL+0x01],#0x0 MOV [HL+0x02],#0x0	001



	MOV [HL+0x03],#		
	MOV [HL+0x04],#	0x000	
	MOV A,H		
	MOV [HL+0x05],A		
	MOV [HL+0x06],#		
	MOV [HL+0x07],#		
	MOV [HL+0x08],#		
	MOV [HL+0x09],#		
	MOV [HL+0x0A],#		
	MOV [HL+0x0B],#		
	MOV [HL+0x0C],#		
	MOV [HL+0x0D],#		
	MOV [HL+0x0E],#		
	MOV [HL+0x0F],#	0x0FF	
	MOV [HL+0x10],#	0x011	
	MOV [HL+0x11],#	0x001	
	MOV [HL+0x12],#	0x010	
	MOV [HL+0x13],#	0x010	
	MOV [HL+0x14],#	0x0AD	
	MOV [HL+0x15],#	0x0FF	
	MOV [HL+0x16],#	0x000	
	MOV A,H		
	MOV [HL+0x17],A		
	MOV [HL+0x18],#	0x003	
	MOV [HL+0x19],#	0x001	
	MOV [HL+0x1A],#	0x010	
	MOV [HL+0x1B],#	0x010	
	MOV [HL+0x1C],#	0x000	
	MOV A,H		
	MOV [HL+0x1D],A	A	
	MOV [HL+0x1E],#	0x0AD	
	MOV [HL+0x1F],#	0x0FF	
	SET1 IDTCEN		
NOHPISE	T_RETURN:		
	POP AX		
	MOV ES,A		
	POP HL		
	POP DE		
	POP AX		
	POP PSW	;for disable interrupt	
	RET	•	

Project Tree	7 × Property Main.c hpi_init.asm
2 🕜 🙎 🔳	10 10 ⇒ →
Grand State (Project)* Grand State (Microcontrolle) Carakora (Build Tool) Carakora (Build Tool) File Build tool generated fi Status hpi_init.asm	2 int g_i=0; 3 int g_i=0; 4 int g_i=0; 5 int g_k=0;
1. Open "main.c"	Double-click "main.c" in the project tree.
2. Write the hot plug-in initialization function	Add the following to the main.c file.
void hpi_initialize_prog(void); int g_i=0; int g_i=0; int g_k=0;	Add this line.
<pre>void main() { hpi_initialize_prog(); wnile(1) { g_i++; g_j++; g_k++; } }</pre>	Add this line.

• Add the lines for calling the hot plug-in initialization function (hpi_initialize_prog) to the main function.



2.2.2 Executing Build Process

- (1) Specifying the Security ID
 - Specify the security ID.

Use the [Common Options] tab in the property panel for the build tool.



1. Open the context menu for "CA78K0R (Build	Select "CA78K0R (Build Tool)" in the project tree and
Tool)"	then right-click it.
2. Open the property panel	Select [Property] from the context menu.
3. Open the [Common Options] tab	Select the [Common Options] tab in the main panel.
4. Specify [Security ID]	Specify [Security ID] under "Device". A desired ID can
	be specified. In this example,
	"000000000000000000" is specified.

- (2) Specifying the Option Bytes
 - Specify the option byte for on-chip debugging.

Use the "Link Options" tab in the property panel for the build tool.

Project Tree	7 × Property main.c hpi_
2 🕜 🤱 🗷	
	Image Columns Line Columns 1 void hpi_initiali 2 void hpi_finitiali Build Project F7 Rebuild Project Shift+F7
	Property
Property 🥤 main.c 🕤 hpi_init.asm	•
CA78K0R Property	
Library	11-in - Receiver01
Vsing libraries	Using libraries[0] System libraries[0]
dditional library paths	Additional library paths[0]
Custors library paths	System library patron
Device	5.
Set enable/disable on-chip debug by link option	Yes[-go]
Option byte values for OCD	HEX 87
Debug monitor area start address	17E00 6.
Debug monitor area size[byte]	
Set user option byte	
Specify mirror area	MAA=0(·m 7.
Set flash start address	No
Boot area load module file name	
Control allocation to self RAM area	No
Control allocation to trace RAM area Control allocation to hot plug-in RAM area	No
Control allocation to not plug-in HAM area	UN
⊞ Message ⊞ Stack	
This option corresponds to the -go option.	mal. For details on this option, refer to the manual of the device.
Common Op Compile Opti Assemble Op	. 🔪 Link Options 🖌 F <mark>OMization 🖌 Object Conv 🖌 Variable</mark>

1. Open the context menu for "CA78K0R (Build Tool)"	Select "CA78K0R (Build Tool)" in the project tree and then right-click it.
2. Open the property panel	Select "Property" from the context menu.
3. Open the [Link Options] tab	Select the [Link Options] tab in the main panel.
4. Expand "Device"	Expand "Device".
5. [Set enable/disable on-chip debug by link option]	Select "Yes".
6. [Option bye values for OCD]	Specify "87".
7. [Debug monitor area size]	Specify "0".
	Note: Specify an appropriate size when normal
	on-chip debugging is done without using the
	hot plug-in function.

[Option Byte Setting for On-chip Debugging]

When using the hot plug-in function, be sure to set the option byte for on-chip debugging to 0x87. The hot plug-in is detected using the low-speed on-chip oscillator. When the above value is specified, the low-speed on-chip oscillator operates and cannot be stopped from the user program. However, only in standby mode, it can be stopped through register settings.



• Specify the user option byte.

Use the [Link Options] tab in the property panel for the build tool.

	Library	
	Using libraries	Using libraries[0]
	System libraries	System libraries[0]
	Additional library paths	Additional library paths[0]
	System library paths	System library paths[0]
Ξ	Device	
	Set enable/disable on-chip debug by link option	Yes(-go)
	Option byte values for OCD	HEX 87
	Debug monitor area start address	💌 17E00 🦰
	Debug monitor area size[byte]	2
	Set user option byte	Yes(-gb)
	User option byte value	60FFE8
	Specify mirror area	MAA=0(-mi0)
	Set flash start address	No
	Boot area load module file name	
	Control allocation to self RAM area	No
	Control allocation to trace RAM area	No
	Control allocation to hot plug-in RAM area	No
	Message	
E	Stack	
Sp	ser option byte value coeffies the user option byte value in hexadecimal without 0x. his option corresponds to the -gb option.	

1. [Set user option byte]	Select "Yes".
2. [User option byte value]	A desired value can be specified. In this
	example, "60FFE8" is specified.

- (3) Allocating RAM for Hot Plug-in
 - Use the [Link Options] tab in the property panel for the build tool to prohibit the user program from using the RAM area that is to be used for hot plug-in.
 - Note: For the product types that do not need RAM allocation to the hot plug-in function, the following item will not appear in the CS+ display. Skip this setting and move to the next step.

🗉 Library	
Using libraries	Using libraries[0]
System libraries	System libraries[0]
E Additional library paths	Additional library paths[0]
E System library paths	System library paths[0]
Device	
Set enable/disable on-chip debug by link option	Yes(-go)
Option byte values for OCD	HEX 87
Debug monitor area start address	HEX 17E00
Debug monitor area size[byte]	0
Set user option byte	Yes(-gb)
User option byte value	HEX 60FFE8
Specify mirror area	MAA=0(-mi0)
Set flash start address	No C
Boot area load module file name	1
Control allocation to self RAM area	No C
Control allocation to trace RAM area	No
Control allocation to hot plug-in RAM area	Yes(Error message)(-ocdhpi)
∃ Message ∃ Stack	
allocation to the hot plug-in RAM area is prohibited specified, a warning is output during the allocation to area is used as an internal RAM area.	g-in RAM area. When "Yes[Error message](-ocdhpi)" is specified, the and an error is output. When "Yes[Warning message](-ocdhpiw)" is the hot plug-in RAM area. When "No" is specified, the hot plug-in RAM tions. And if this option is set, consider a -set/-set/w, -ocdtr/-ocdtrw

1. [Control allocation to hot plug-in	Select "Yes(Error message)".
RAM area]	

- (4) Executing the Build Process
 - Settings of edit and build tool options have been completed. Execute the build process.





2.2.3 Writing and Executing Program

- (1) Writing a Program
 - Write the created hex file to the target device through the Renesas Flash Programmer.

For usage of the Renesas Flash Programmer, refer to the user's manual that can be found by selecting [Start] \rightarrow [Programs] \rightarrow [Renesas Electronics Utilities] \rightarrow [Programming Tools] \rightarrow [Renesas Flash Programmer Vx.xx].



- (2) Executing the Program
 - Supply power to the user system and execute the program on the actual device.



User system

2.2.4 Hot Plug-in Connection

- (1) Connecting the Hot-Plug Adapter (R0E000010ACB00) to the User System
 - Be sure to connect the R0E000010ACB0 to the user system first.

The R0E000010ACB00 has a mechanism that ensures that connection to the E1 emulator begins with the GND line.



- (2) Connecting the E1 Emulator to the Host PC
 - Connect the E1 to the host PC.



- (3) Making Debugging Function Settings
 - Select a debug tool in CS+.

Project Tree 4 Project Tree 4 Projec	Image: second secon
1. Open the context menu for "Debug Tool"	Select "Debug Tool" in the project tree and then right-click it.
2. Select a debug tool	Select [Using Debug Tool] \rightarrow [RL78 E1(Serial)].

• Specify the security ID for authentication of E1 emulator connection. In addition, specify retry settings for the hot plug-in function.



1. Open the property panel for "Debug Tool"	Select "Debug Tool" in the project tree and then right-click it.
2. Enter the security ID for authentication.	Specify [Security ID] under "Flash" in the [Connect Settings] tab. Enter the same value as that specified as a common option for the build tool. In this example, enter "00000000000000000000".
3. Make retry settings for hot plug-in	Hot plug-in connection may fail when the low-speed on-chip oscillator stops due to, for example, the CPU being in the STOP mode. For such a case, specify the interval and number of hot plug-in retries. Since the program in this example does not stop the low-speed on-chip oscillator, these settings are left as the default values (1000 ms and three times).

[Retry Settings for Hot Plug-in]

• For the retrying interval, enter the longest period for which the STOP mode continues in the program. Note that the debugger cannot be operated during the retry processing (retrying interval × number of retries).

Therefore, be careful not to make the retry processing period extremely long.

• Specify the RAM monitoring interval.



1. Open the context menu for "Debug Tool"	Select "Debug Tool" in the project tree and then right-click it.
2. Open the property panel	Select [Property].
3. Specify [Display update interval]	Specify [Display update interval] under "Access Memory While Running" in the [Debug Tool Settings] tab. A value of 100 ms or greater can be specified. In this example, "500" is specified.

- (4) Executing Hot Plug-in Connection
 - Prepare for hot plug-in connection.

🚺 sample - CubeSuite+ - [P	roperty]		
File Edit View Project Bu	iik Del	bug To <mark>pl Window Help</mark>	
🚳 Start 🛛 🛃 🗐	× D	Download	
Project Tree		Build & Downin 1.	F6
2 🕜 🙎 🔳		Connect to Debug Tool	
□ <mark> R</mark> sample (Project)* R5F10PMF (Microc CA78K0R (Build To RL78 E1(Serial) (Del	-	Hot Plug-in	
		Upload	
	- N	Disconnect from Debug Tool	Shift+F6
E. File		Stop	Shift+F5
1. Shift the debugger to the hot	Seleo	ct [Hot Plug-in] from the	[Debug] mer
plug-in preparation state			

• Check that the following dialog appears.



• Connecting the E1 emulator to the hot-plug adapter (R0E000010ACB00)

Connect the E1 to the R0E000010ACB00. Connect the E1 emulator and hot-plug adapter while the connectors are correctly aligned on both sides.



• Hot plug-in connection

After connecting the emulator, click the [OK] button on the following box.

	Question(Q0	204001)	
	?	Hot Plug-in is prepared. Connect the debug target to a PC and click OK.	
		1. OK Cancel <u>H</u> elp	
1. Hot plug-in con	nection	Click the [OK] button.	

[Unavailable Functions after Hot Plug-in Connection]

The following functions cannot be used after hot plug-in connection. To enable them, execute a forced break after hot plug-in connection.

- Trace function
- Input signal masking function
- Event break function/sequential break function
- Software break function
- Settings regarding whether to operate or stop emulation of peripheral timer and serial modules while execution is stopped



2.2.5 Debugging

- (1) Memory Display Update Function
 - Open the memory panel.



1. Open the memory panel	Open the [View] menu and select [Memory] \rightarrow [Memory 1].
2. Check the memory panel where the RAM monitor function works	The values on the memory panel are displayed in pink and the display is updated periodically.

- (2) Displaying Global Variables
 - Register a variable from the source.



1. Register a global variable in the watch panel	Drag and select "g_i" in the main.c source and right-click it. Then, select [Register to Watch1".
2. Check the variable registered in the watch panel	The value of the variable is updated periodically.

- (3) Forced Break
 - Break execution of the program.



- (4) Debugging Functions after Break
 - Software break

During program execution, a break occurs where a breakpoint is specified.



1. Specify a software break	Click the break setting column for the "g_j++;" line on the main.c source display.
2. Check occurrence of the software break	Execute the program and check that the specified software break occurs.



Access break

This function generates a break when a specified value is written to, read from, or written to/read from a variable.



1. Open the context menu	Drag and select "g_i" on the main.c source and right-click it.
2. Specify an access break	Select [Break Settings] \rightarrow [Set Write Combination Break to] and specify the value that generates a break. A desired value can be specified. In this example, specify "0x01".
3. Check occurrence of the access break	When an access break occurs, execution of the program will stop and the accessed address and value will be displayed.



2.2.6 Disconnecting from User System

(1) Disconnecting the Debug Tool

Disconnect the debug tool.

- Notes: 1. Before disconnection, stop program execution.
 - 2. When the debug tool is disconnected, a reset is applied to the microcontroller. After disconnection, the reset state continues as long as the emulator is connected.
 - 3. To use the hot plug-in function again after disconnection, disconnect the E1 from the user system, reset the microcontroller, and then execute hot plug-in connection.



1. Disconnect the debug tool	Break execution of the program and click the
	[Disconnect] button on the menu bar.

- (2) Turning off the User System
 - Power off the user system.
- (3) Disconnecting the E1 Emulator
 - Disconnect the USB cable from the E1 emulator and the host PC.
 - Then, disconnect the E1 emulator from the user system.
- (4) Terminating the CS+
 - Terminate CS+.



3. Notes

3.1 Note on Debug DTC Operating Clock

Supply of the clock for operating the debug DTC is specified through the DTCEN bit in the same way as the clock for the normal DTC. Therefore, do not clear the DTCEN bit to 0 before using the hot plug-in function or RRM/DMM using the DTC.

3.2 Note on DTC Suspending Instructions

Since the hot plug-in function and RRM/DMM using the DTC are implemented by using the DTC, when multiple DTC suspending instructions continue, start of the DTC is suspended. If the start of the DTC continues to be suspended, hot plug-in connection or RRM/DMM will fail.

[DTC suspending instructions]

- a) Unconditional branch instructions b) Call/return instructions
- c) Conditional branch instructions d) Instructions for read access to the code flash area
- e) Bit manipulation instructions for IFxx, MKxx, PRxx, and PSW and 8-bit manipulation instructions including the ES register as an operand

Especially when an infinite loop processing is specified in the C language, note that the code is expanded to the assembly language as follows.



In this case, modify the code so that DTC suspending instructions do not continue; for example, insert a NOP instruction in the infinite loop as follows.



3.3 Note on Data Access Event

When RRM/DMM using the DTC is used, if a data access event is specified for a target variable of RRM/DMM or for an SFR, the following events will occur at RRM/DMM access.

- Event break (including sequential break)
- Trace start/stop event

When a data access event is specified for a variable or an SFR, do not use RRM/DMM using the DTC for that variable or SFR.

3.4 Note on Access to a 32-Bit or Longer Variable

The maximum data size in the DTC used in RRM/DMM using the DTC is 16 bits.

Therefore, when reading from or writing to a 32-bit or longer variable conflicts with writing to the variable by the CPU, the read or written value may be wrong.

For example, when a 32-bit variable is read, if the CPU writes to the variable between the upper 16-bit reading and lower 16-bit reading, the data before and after writing are read as the upper 16 bits and the lower 16 bits, respectively.

3.5 Notes on Standby Mode

Pay attention to the following notes on standby mode.

• Before hot plug-in connection

When the MCU enters the standby mode before connection and either the low-speed on-chip oscillator or DTC operating clock stops, hot plug-in connection is disabled.

- When hot plug-in connection is disabled due to standby mode, use the retry settings.
- After hot plug-in connection

When the MCU enters the STOP mode after hot plug-in connection and the source of the DTC operating clock is not the high-speed on-chip oscillator, RRM/DMM using the DTC is suspended while the MCU is in the STOP mode. (RRM/DMM using the DTC is resumed when the STOP mode is canceled.) Note that the debugger uses the time specified for [Retrying interval] in the retry settings as the maximum period for suspension of RRM/DMM using the DTC. (If the STOP mode continues for the retrying interval, an error will occur.)

3.6 Notes on Reset

Pay attention to the following notes on reset.

- Reset by the POR circuit while program execution is stopped After hot plug-in connection, if a reset is applied by the POR circuit while program execution is stopped, the user program runs for about 900 ms after the reset occurs and then stops.
 - * This is because the user program can be stopped only after execution of the hot plug-in initialization program is completed.
- Reset by the POR circuit or pin reset during program execution After hot plug-in connection, if a reset by the POR circuit or a pin reset occurs during program execution, the following settings become disabled.
 - Hardware break settings (events are disabled)
 - Trace function (events are disabled and tracing is stopped)
 - Masking of input signals (all mask settings are disabled)

When software break is used, if a reset by the POR circuit or a pin reset occurs and the instruction where a software breakpoint is set is executed before hot plug-in connection is done again, a reset due to execution of the 0xFF code will occur.

Note that even after hot plug-in connection, the pin reset masking function can be used after a forced break is done. Therefore, if the above-described behavior is a problem, use the pin reset masking function instead.

 Internal reset during program execution (except for the reset by the POR circuit and pin reset) After hot plug-in connection, if an internal reset occurs during program execution, RRM/DMM using the DTC will stop. After the time specified as the retrying interval has passed, RRM/DMM using the DTC will resume.

3.7 Note on RAM Usage

In some device types, an appropriate RAM area should be allocated to use the hot plug-in connection, RRM/DMM using the DTC, or trace function. For details, refer to the hardware manual(On-chip Trace) for each MCU.



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Revision History

		Description		
Rev.	Date	Page	Summary	
2.00	Aug. 20, 2013		English version created from Japanese revision 2.00.	
3.00	Aug. 26, 2016		Changed CubeSuite+ to CS+	
		1	Addition of RL78/F15.	
		10	Addition of the hot plug-in initialization function for "CS+ for	
			CC".	
4.00	Dec. 20, 2023	11	Addition of the hot plug-in initialization function for "RL78/F2x".	

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power is supplied until the power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.)

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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